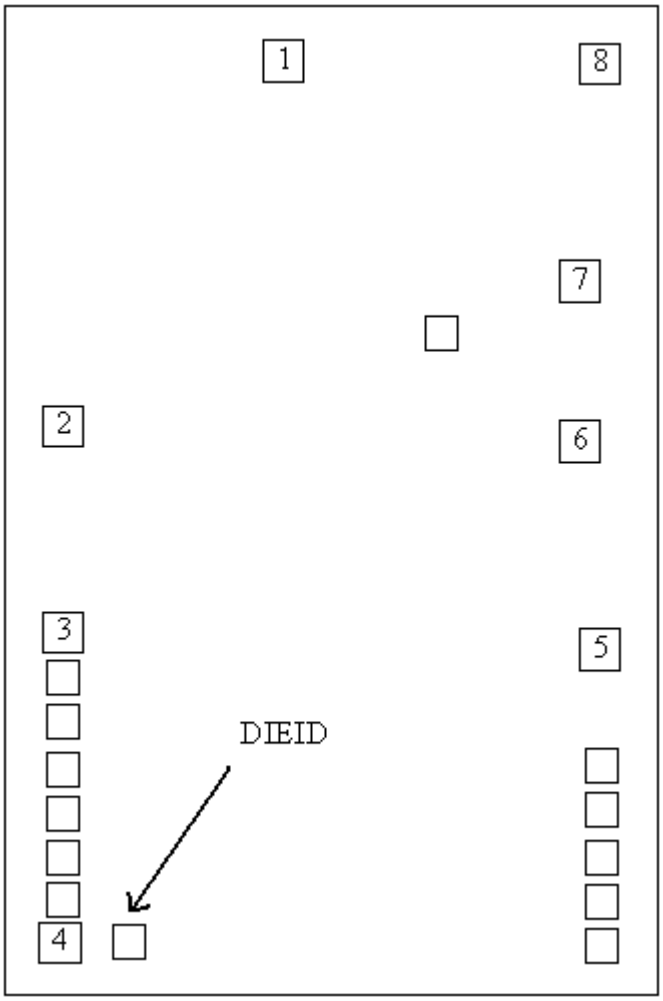
LM3478 MDC MWC

HIGH EFFICIENCY LOW-SIDE N-CHANNEL CONTROLLER FOR SWITCHING REGULATOR

May 30,2006

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM3478A	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	A	Bond Pad Metalization	0.5%COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1473µm x 2235µm 58.0mils x 88.0mils	Back Side Connection	AGND
Thickness	216µm Nominal		
Min Pitch	362µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
I_{SEN}	1	-107	995	92	x	92
COMP	2	-607	170	92	x	92
FB	3	-607	-298	92	x	92
AGND	4	-613	-999	92	x	92
PGND	5	607	-336	92	x	92
DR	6	563	134	92	x	92
FA/SD	7	563	497	92	x	92
V_{IN}	8	607	988	92	x	92

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